



Title of Change:	Final PCN for wafer fabrication site addition of ON Semiconductor Niigata Co., Ltd. In Niigata, Japan (Group JG)																																																
Proposed first ship date:	19 September 2015																																																
Contact information:	Contact your local ON Semiconductor Sales Office or <Yasuhiro.Igarashi@onsemi.com>																																																
Samples:	Contact your local ON Semiconductor Sales Office																																																
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <Kazutoshi.Kitazume@onsemi.com>.																																																
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <PCN.Support@onsemi.com>.																																																
Change Part Identification:	Affected products will be identified with date code.																																																
Change category(s): ☒ Wafer Fab Change ☒ Manufacturing Site Change/Addition ☐ Product specific change ☐ Assembly Change ☐ Manufacturing Process Change ☐ Datasheet/Product Doc change ☐ Test Change ☐ Material Change ☐ Shipping/Packaging/Marking ☐ Other: _____																																																	
Sites Affected: ☐ All site(s) ☐ not applicable ☒ ON Semiconductor site(s) : ☐ External Foundry/Subcon site(s):		Site 1 ON Niigata, Japan Site 2																																															
Description and Purpose: This is a Final Process Change Notification to announce the addition of a new wafer fabrication site for the device covered in this notice. Device formerly manufactured at the Manufacturers UMC will be manufactured at ON Semiconductor Niigata Co., Ltd. (OSNC) following the expiration of this notice. OSNC located in Niigata, Japan has obtained ISO9001 certification. The product design and electrical specifications will remain identical. A full electrical characterization over the temperature range will be performed to check the device functionality and electrical specifications. Qualification tests are designed to show that the reliability of transferred devices will continue to meet or exceed ON Semiconductor standards.																																																	
Reliability Data Summary: <table border="1"> <thead> <tr> <th>Test:</th> <th>Conditions:</th> <th>Interval:</th> <th>Results:</th> <th>Quantity</th> </tr> </thead> <tbody> <tr> <td>Steady State Operating Life</td> <td>Tj=150degC</td> <td>1000 hrs</td> <td>Pass</td> <td>0/22</td> </tr> <tr> <td>High Temperature Reverse Bias</td> <td>Ta=150degC, VDSS =max</td> <td>1000 hrs</td> <td>Pass</td> <td>0/22</td> </tr> <tr> <td>Temp Humidity Storage</td> <td>Ta=85degC, RH=85%</td> <td>1000 hrs</td> <td>Pass</td> <td>0/22</td> </tr> <tr> <td>Temperature Cycle</td> <td>Ta=-55degC to 150degC 30min each</td> <td>100 cycles</td> <td>Pass</td> <td>0/22</td> </tr> <tr> <td>Pressure Cooker</td> <td>Ta=121degC, 2.03×105Pa, 100%</td> <td>50 hrs</td> <td>Pass</td> <td>0/22</td> </tr> <tr> <td>High Temperature Storage</td> <td>Ta=150degC</td> <td>1000 hrs</td> <td>Pass</td> <td>0/22</td> </tr> <tr> <td>Resistance to Soldering heat(Reflow)</td> <td>Solder Temp.: 260degC±5degC</td> <td>10 s</td> <td>Pass</td> <td>0/22</td> </tr> <tr> <td>Solderability</td> <td>Solder Temp.: 245degC±5degC</td> <td>5 s</td> <td>Pass</td> <td>0/22</td> </tr> </tbody> </table>					Test:	Conditions:	Interval:	Results:	Quantity	Steady State Operating Life	Tj=150degC	1000 hrs	Pass	0/22	High Temperature Reverse Bias	Ta=150degC, VDSS =max	1000 hrs	Pass	0/22	Temp Humidity Storage	Ta=85degC, RH=85%	1000 hrs	Pass	0/22	Temperature Cycle	Ta=-55degC to 150degC 30min each	100 cycles	Pass	0/22	Pressure Cooker	Ta=121degC, 2.03×105Pa, 100%	50 hrs	Pass	0/22	High Temperature Storage	Ta=150degC	1000 hrs	Pass	0/22	Resistance to Soldering heat(Reflow)	Solder Temp.: 260degC±5degC	10 s	Pass	0/22	Solderability	Solder Temp.: 245degC±5degC	5 s	Pass	0/22
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Electrical Characteristic Summary: There is no change in the electrical performance. Datasheet specifications remain unchanged.																																																	
List of Affected Standard Parts: ATP114-TL-H ATP404-TL-H ATP404-H-TL-H																																																	